



FILE GODY

December 28, 2000

To:

Assistant Commissioner of Patents Office of Initial Patent Examination

Customer Service Center Washington, D.C. 20231

From: Stephen B. Ackerman

Subject:

Serial No.: 09/684,519
Filing Date: 10/10/2000
Inventor: J. Y. Lee
Title: Thermally Compliant PCB Substrate for the Application of Chip Scale

Packages

REQUEST TO CORRECT FILING RECEIPT

Dear Sir:

On the copy of the enclosed Filing Receipt, there are errors in the list of Applicants and the Title. The first Applicant's name is misspelled. Mr. Lee's corrected name and residence reads; Jin-Yuan Lee, Hsin-Chu, Taiwan. Acronyms in the Title should be capitalized. The corrected Title reads: Thermally compliant PCB substrate for the application of chip scale packages.

Please make the necessary changes to correct the errors on the Filing Receipt.

If there are any questions, please contact the undersigned attorney at (845) 452-5863. Thank you for your attention to this matter.

Respectfully Submitted,

Stephen B. Ackerman, Reg. No. 37,761



UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 2023I
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APPLICATION NUMBER FILING DATE **GRP ART UNIT** FIL FEE REC'D ATTY.DOCKET.NO DRAWINGS TOT CLAIMS IND CLAIMS MEG2000-09/684,519 10/10/2000 2841 823 3 72 2 001

George O Saile 20 McIntosh Drive Poughkeepsie, NY 12603 Date Mailed: 12/08/2000

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the PTO processes the reply to the Notice, the PTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)
Yin-Yuan Lee, Hsin-Chu, TAIWAN;

Continuing Data as Claimed by Applicant

Foreign Applications

If Required, Foreign Filing License Granted 12/07/2000

** SMALL ENTITY **

Title

Thermally compliant pcb substrate for the application of chip scale packages

Preliminary Class

361

Data entry by: BALL, ROSALIND

Team: OIPE

Date: 12/08/2000



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Bib Data Sheet

CONFIRMATION NO. 3369

SERIAL NUMBER 09/684,519	FILING DATE 10/10/2000 RULE	CLASS 361	· ·	UP ART UNIT 2841		ATTORNEY DOCKET NO. MEG2000-001	
#* CONTINUING DATA **********************************							
GRANTED ** 12/07/2000 Foreign Priority claimed 35 USC 119 (a-d) conditions yes no Met after Met after Ollows 2000 Met after COUNTRY DRAW			SHEETS DRAWING	TOTAL CLAIMS 72		INDEPENDENT CLAIMS 2	
ADDRESS George O Saile 20 McIntosh Drive Poughkeepsie ,NY 12603							
TITLE Thermally compliant PCB substrate for the application of chip scale packages							
FILING FEE FEES: Authority has been given in Paper RECEIVED No to charge/credit DEPOSIT ACCOUNT No for following:				All Fees 1.16 Fees (Filing) 1.17 Fees (Processing Ext. of time) 1.18 Fees (Issue) Other Credit			